

ELEP HOLDER

ELP NBD-5170K

Features

- For package dicing process
- Expand type

Structure



Properties

Table.1 General properties

Item	Unit	ELP NBD-5170K
Color	—	Translucent
Total thickness	μ m	170
Adhesion on Si wafer before UV	N/20mm	14.7
Adhesion on Si wafer after UV		0.1

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ELP NBD-5170K-e 1/1
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